



# Product Change Notification



Product Group: Vishay Siliconix/July 11, 2012/PCN-SIL-0202012

## TO-247 Alternate Lead-Frame

**DESCRIPTION OF CHANGE:** This notification is made to advise users of parts packaged in the TO-247 that an alternative lead frame design has been qualified for use by manufacturing. The qualification of this lead-frame results in a minor change to the A2 dimension of the POD. The list of Mosfet devices that may be affected by this change are listed below. The updated POD is also shown below for reference.

**CLASSIFICATION of CHANGE:** Update to documentation

**REASON FOR CHANGE:** Manufacturing flexibility.

**EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE:** This change will have no affect in quality, reliability, or performance of devices using this package.

**PRODUCT CATAGORY:** Commercial Power MOSFETs in TO-247 packages

**PART NUMBERS/SERIES/FAMILIES AFFECTED:** see list below

**VISHAY BRAND(s):** Vishay Siliconix

**TIME SCHEDULE:** Shipments of products using the alternate lead frame will begin after October 11, 2012.

**SAMPLE AVAILABILITY:** Samples will be available for customer qualification in July, 2012.

**QUALIFICATION DATA:** Qualification and device performance data will be available upon completion.

**PRODUCT IDENTIFICATION:** There will be no changes to part marking. Products built with the alternate lead-frame will have part marking in the form of **Y27zab** where the **Y** is the factory designator for Vishay Xian.

**This PCN is considered approved, without further notification, unless we receive specific customer concerns before October 11, 2012 or as specified by contract.**

**ISSUED BY:** Don Larson, Vishay Siliconix, Technical Marketing Manager. E-mail address: [Don.larson@Vishay.com](mailto:Don.larson@Vishay.com)

**For further information, please contact your regional Vishay office.**

### CONTACT INFORMATION:

#### The Americas

Vishay Americas  
2201 Laurelwood Rd  
Santa Clara, Ca 95054  
T: 408-567-8500  
F: 2408-567-8942

#### Europe

Vishay Electronic GmbH  
Geheimrat-Rosenthal-Strasse 100  
D-95100  
Selb, Germany  
T: 49-9287-71 0  
F: 49-9287-70435

#### Asia

Vishay Intertechnology Asia Pte. Ltd  
25 Tampines Street 92  
#02-00 Keppel Building  
Singapore 52887  
T: 65-6780-7838  
F: 65-6780-7791

Vishay Intertechnology, Inc.

Corporate Headquarters 63 Lincoln Highway, Malvern, PA 19355-2143 U.S.A. Phone (610) 644-1300 Fax (610) 296-0657 [www.vishay.com](http://www.vishay.com)

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Procedure #



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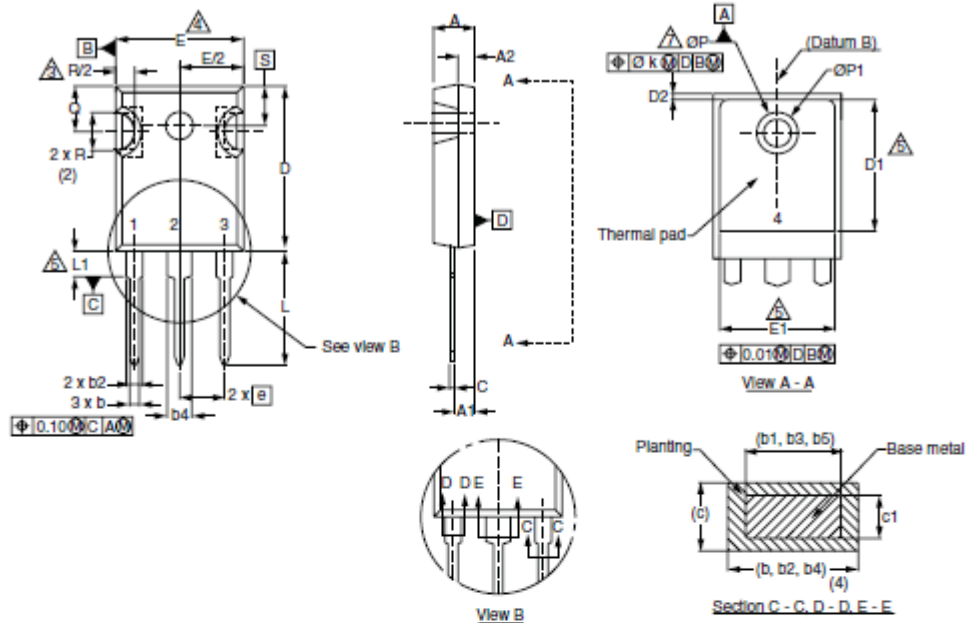
List of Active Parts Affected by Change			
IRFP048	IRFP264	IRFP460A	IRFPF50
IRFP048PBF	IRFP264PBF	IRFP460APBF	IRFPF50PBF
IRFP048RPBF	IRFP26N60L	IRFP460LC	IRFPG30
IRFP054	IRFP26N60LPBF	IRFP460LCPBF	IRFPG30PBF
IRFP054PBF	IRFP27N60K	IRFP460PBF	IRFPG40
IRFP064	IRFP27N60KPBF	IRFP9140	IRFPG40PBF
IRFP064PBF	IRFP31N50L	IRFP9140PBF	IRFPG50
IRFP140	IRFP31N50LPBF	IRFP9240	IRFPG50PBF
IRFP140PBF	IRFP32N50K	IRFP9240PBF	SIHG16N50C-E3
IRFP150	IRFP32N50KPBF	IRFPC40	SIHG20N50C-E3
IRFP150PBF	IRFP340	IRFPC40PBF	SIHG22N60E-E3
IRFP17N50L	IRFP340PBF	IRFPC50	SIHG22N60S-E3
IRFP17N50LPBF	IRFP350	IRFPC50A	SIHG24N65E-E3
IRFP21N60L	IRFP350LC	IRFPC50APBF	SIHG30N60E-E3
IRFP21N60LPBF	IRFP350LCPBF	IRFPC50LC	SIHG47N60E-E3
IRFP22N50A	IRFP350PBF	IRFPC50LCPBF	SIHG47N60S-E3
IRFP22N50APBF	IRFP360	IRFPC50PBF	94-1730
IRFP22N60K	IRFP360LC	IRFPC60	94-2574PBF
IRFP22N60KPBF	IRFP360LCPBF	IRFPC60LC	94-3257
IRFP23N50L	IRFP360PBF	IRFPC60LCPBF	94-5851PBF
IRFP23N50LPBF	IRFP440	IRFPC60PBF	SiHG47N60E-GE3
IRFP240	IRFP440PBF	IRFPE30	SiHG22N60E-GE3
IRFP240PBF	IRFP448	IRFPE30PBF	SiHG30N60E-GE3
IRFP244	IRFP448PBF	IRFPE40	SiHG24N65E-GE3
IRFP244PBF	IRFP450	IRFPE40PBF	SiHG25N40D-GE3
IRFP250	IRFP450A	IRFPE50	SiHG17N60D-E3
IRFP250PBF	IRFP450APBF	IRFPE50PBF	SiHG17N60D-GE3
IRFP254	IRFP450LC	IRFPF30	IRFP460BPBF
IRFP254PBF	IRFP450LCPBF	IRFPF30PBF	SiHG460B-GE3
IRFP260	IRFP450PBF	IRFPF40	
IRFP260PBF	IRFP460	IRFPF40PBF	



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## TO-247AC (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.65	5.31	0.183	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	1.37	0.046	0.054
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.65	2.39	0.065	0.094
b3	1.65	2.37	0.065	0.093
b4	2.59	3.43	0.102	0.135
b5	2.59	3.38	0.102	0.133
c	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.70	0.776	0.815
D1	13.08	-	0.515	-

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
E	15.29	15.87	0.602	0.625
E1	13.72	-	0.540	-
e	5.46 BSC		0.215 BSC	
$\phi k$	0.254		0.010	
L	14.20	16.10	0.559	0.634
L1	3.71	4.29	0.146	0.169
N	7.62 BSC		0.300 BSC	
$\phi P$	3.56	3.66	0.140	0.144
$\phi P1$	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51 BSC		0.217 BSC	

ECN:  
DWG:

### Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Contour of slot optional.
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
4. Thermal pad contour optional with dimensions D1 and E1.
5. Lead finish uncontrolled in L1.
6.  $\phi P$  to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
7. Outline conforms to JEDEC outline TO-247 with exception of dimension A2